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[Continued on next page]

(54) Title: HIGH SPEED COPPER PLATING BATH

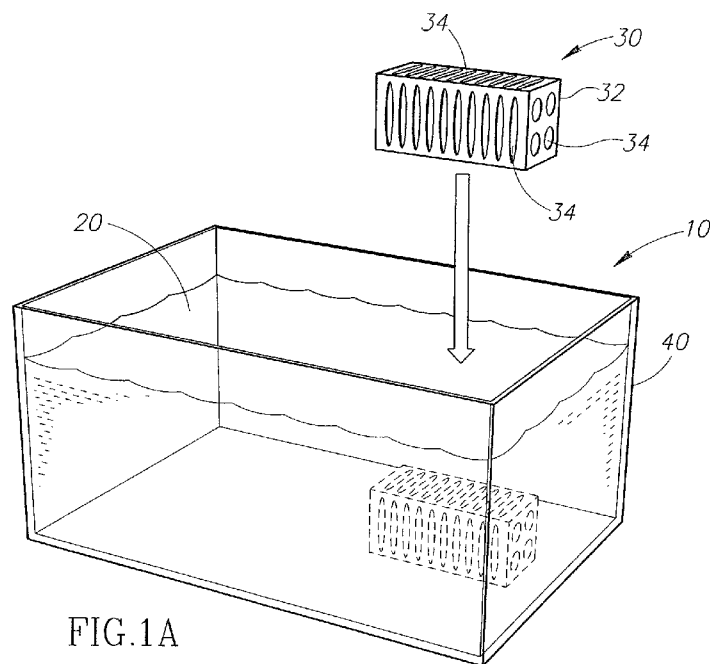


FIG. 1A

(57) Abstract: Copper electroplating bath that includes an aqueous solution that comprises a copper salt and at least one acid and a container that comprises a copper salt in solid form, is disclosed. The container supplies copper ions to the aqueous solution to maintain the copper ion concentration of the aqueous solution at saturation levels while retaining the copper salt in solid form within the container.



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